

WHAT IS CLAIMED IS:

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1. A liquid-crystal display unit comprising:
a first board having a signal line, a scanning line and a pixel electrode;
10 a second board having a common electrode, the second board opposing said first board;
a liquid-crystal layer provided between said first board and said second board; and
a third board having at least one of a
15 signal-line driver driving said signal line and a scanning-line driver driving said scanning line, the third board being separate from said first board and said second board.

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25 2. The liquid-crystal display unit as claimed in claim 1, wherein said third board is formed of a same material as said first board.

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3. The liquid-crystal display unit as claimed in claim 1, wherein said third board is connected to said first board by a flexible cable.

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4. The liquid-crystal display unit as

claimed in claim 1, wherein said third board is connected to said first board by a wire bonding.

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5. The liquid-crystal display unit as claimed in claim 1, wherein said third board is connected to said first board by a flip-chip bonding.

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6. A method of manufacturing a liquid-crystal display unit including: a first board having a signal line, a scanning line and a pixel electrode; a second board having a common electrode, the second board opposing said first board; and a liquid-crystal layer provided between said first board and said second board, the method comprising the steps of:

forming said signal line, said scanning line, said pixel electrode, and at least one of a signal-line driver driving said signal line and a scanning-line driver driving said scanning line on a same substrate; and

dividing said same substrate into said first board and a third board having at least one of said signal-line driver and said scanning-line driver.

35 7. The method as claimed in claim 6,
wherein said step of forming forms said signal line,
said scanning line, said pixel electrode, and at

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least one of said signal-line driver and said scanning-line driver in a same process.

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8. The method as claimed in claim 6,
further comprising the step of connecting said third
board to said first board by a flexible cable.

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9. The method as claimed in claim 6,
15 further comprising the step of connecting said third
board to said first board by a wire bonding.

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10. The method as claimed in claim 6,
further comprising the step of connecting said third
board to said first board by a flip-chip bonding.

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